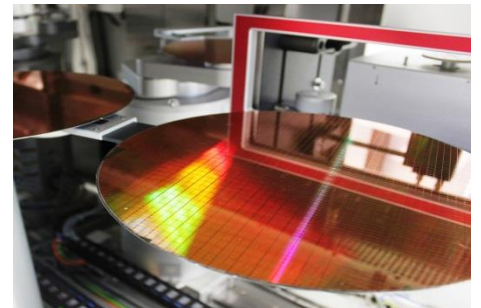




The InnoLas **Wafer Marking System IL C3000**
for the unique Identification of your wafers



Laser and Optics

Laser Type	Nd:YAG 355/532/1064 & CO ₂ 10.600nm
Laser Class	Class 1 / Class 4 with open cabinet
Focus Lens	F-Theta Objective
Galvo Head	High precision digitally controlled unit
Laser Stability	±1% peak to peak

Marking

Fonts	Dot Matrix	SEMI OCR 5x9 / 10x18 / 15x27
	Barcode	SEMI BC412, IBM BC412
	2D Code	SEMI T7
	Engraved Mode	
Checksum	SEMI / IBM / customized (optional)	
Serialization	Numeric / Alphanumeric / IBM	
Text Position	Adjustable in X-, Y-Axis and Angle	
Repeatability X and Y-direction	±75 µm (high precision) / ±100 µm (standard)	
Dot Depth	0,1 – 100µm (depending on laser & material)	
Dot Diameter	25 – 150 µm (depending on laser & material)	

Handling System

Wafer Sizes	300 mm
Wafer Transfer	Single Arm Robot – Single End Effector
Wafer Alignment	Opto-mechanical
Wafer Handling	Vacuum / Edge Grip (optional)
Loading Stations	Up to 3
Throughput (wafers/hr)	120 (SEMI M12 spec. w/o reading)

Facility Requirements

Electrical	230 V (1P/1N/1PE) / 50 Hz / 16 Amps Optional: 115-200-240-370-380-400-420-480V	
Power Consumption	1500 W	
Communication	Ethernet RJ45 (SECS/GEM optional)	
Vacuum	-800 mbar	/ 8mm OD connection
Exhaust	33,6 m ³ /hr	/ 50 mm ID connection
CDA – Compressed Dry Air	6 bar	/ 8mm OD connection
PFO – Process Fluid Outlet	8mm OD connection	
Cooling Water (optional)	> 5 l/min at 15°C	
Water Pressure	2-6 bar	
Weight	1200 kg	
Dimension (w x l x h)	1648 x 2092 x 2196 mm	

General

System Frame	Stainless Steel
System Panels	Powder coated
Mini Environment	ISO 3 (ISO 14644-1) / Class 1 (US FED STD 209E)
Certification	CDRH #0010530 / CE